BQCSD-XXXXMF-XXXXT - 4x2.5 Crystals



FEATURES

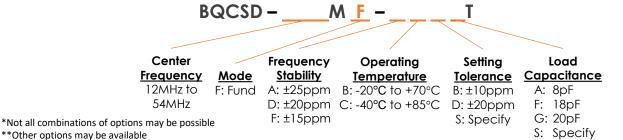
SMD Construction Standard 4x2.5mm Package Size

High Stability Over Temp

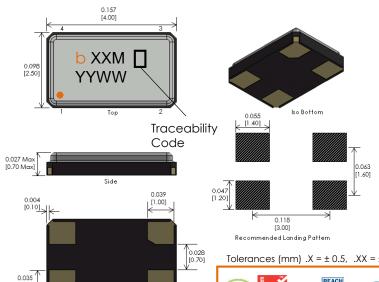
Crystals

#blileytakesyoufurther

Part Number Configuration



Physical Specifications



PIN	FUNCTION		
1	Crystal		
2	Ground		
3	Crystal		
4	Ground		

Tolerances (mm) $.X = \pm 0.5$, $.XX = \pm 0.2$ unless otherwise specified



- Connection Pads: Gold(10-40 µ in.) 1) over Nickel (100-250 µ in.)
 - 2) Weight = 1.5gms typical

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Performance Specifications

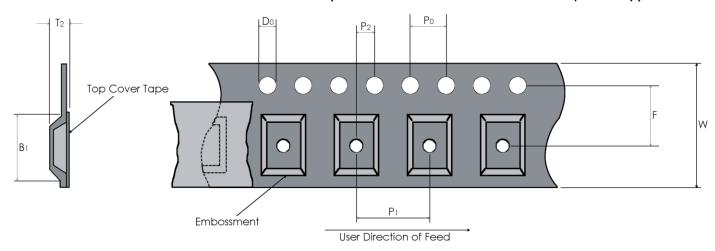
Parameter	Conditions	Min	Тур	Max	Unit
Frequency Range	Fundamental	12		54	MHz
Setting Tolerance	@ + 25°C	±50 N	1ax (see op	otions)	ppm
Frequency Stability		±100 N	Max (see o	otions)	ppm
Aging	1 st Year			±3.0	ppm
	12.0 – 14.9 MHz 80			Ω	
Equivalent Series Resistance (max)	15.0 – 29.9 MHz	50			Ω
Resistance (max)	30.0 – 54.0 MHz	40			Ω
Drive Level			10	100	μW
C0 (Shunt Capacitance)				5.0	рF
CL (Load Capacitance)	Per Option (typical)	8-3	2 (see optio	ons)	рF
DLD	50nW to 100µW			±10	ppm
RLD	50nW to 100µW			20%	Ω
Operating Temp Range	See Options	-20 to	+70 / -40 t	0 +85	°C
Storage Temp Range		-55		+105	°C
Sealing Method	aling Method Seam Weld			k	
Moisture Sensitivity Level	1				

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Tape and Reel

Embosed Carrier Dimensions (8mm, 12mm, 16mm, 24mm Tape Only)



Tape Dimensions (mm) Reel Dimensions (mm)									sions (mm)
W	F	Do	Ро	Р1	P2	В1	T2	Outside Dia.	Parts / Reel
12	4.5	1.5	4.0	8.0	2.0	4.3	1.0	180	1,000

Recommended Reflow Profile

Reflow Profile: in accordance to IPC/JEDEC J-STD-020 (Latest Revision)

Additional Notes:

- This part has been designed for pick and place reflow soldering
- This part may be reflowed once
- This part should not be reflowed in the inverted position

Packaging

Packaging: All packaging must conform to ESD Controls detailed in ANSI/ESD S20.20 (Latest Revision)

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